

Serial No. 10/678,419

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Reply to the Office Action dated October 18, 2004

Page 2 of 14

AMENDMENTS TO THE SPECIFICATION:

Please replace the paragraph no. [0020] with the following paragraph:

[0020] The flip-chip BGA package 120 will now be described in more detail with reference to the sectional view of the flip-chip BGA package 120 of Figure 2. The flip-chip BGA package 120 includes the substrate 122 of a BT resin/glass epoxy printed circuit board 440 with conductive traces for signal transfer. The conductive traces are typically copper and connect the interconnect pads on the first side of the substrate 122 and contact pads on the second side of the substrate 122. Interconnect pads and contact pads are connected by the copper conductive traces of the substrate 122 that extend therebetween. The interconnect pads connect with the solder ball electrical connectors 126 of the semiconductor die 124 and the contact pads connect with the contact balls 128 of the ball grid array. A solder mask is deposited on the upper and lower surface of the substrate 122, with the interconnect pads and the contact pads of the conductive traces exposed.